



TPL5010 Nano-power System Timer with Watchdog Function

1 Features

- Supply Voltage from 1.8V to 5.5V
- Current Consumption at 2.5V 35nA (typ)
- Selectable Time Intervals 100ms to 7200s
- Timer Accuracy 1% (typ)
- Resistor Selectable Time Interval
- Watchdog Functionality
- Manual Reset

2 Applications

- Battery Powered Systems
- Internet of Things (IoT)
- Intruder Detection
- Tamper Detection
- Home Automation Sensors
- Thermostats
- Consumer Electronics
- Remote Sensors
- White Goods

3 Description

The TPL5010 Nano Timer is a low power timer with a watchdog feature ideal for system wake up in duty cycled or battery powered applications. In such systems the μ C timer can be used for system wake-up, but if the timer sleep current is high, up to 60-80% of the total system current can be consumed by the μ C timer in this sleep mode. Consuming only 35nA, the TPL5010 can replace the functionality of the integrated μ C timer and allow the μ C to be placed in a much lower power mode. Such power savings enable the use of significantly smaller batteries making it well suited for energy harvesting or wireless sensor applications. The TPL5010 provides selectable timing intervals from 100ms to 7200s and is designed for interrupt-driven applications. Some standards (such as EN50271) require implementation of a watchdog for safety and the TPL5010 realizes this watchdog function at almost no additional power consumption. The TPL5010 is available in a 6-pin SOT23 package.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPL5010	SOT23 (6)	3.00 mm x 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

4 Simplified Application Schematic

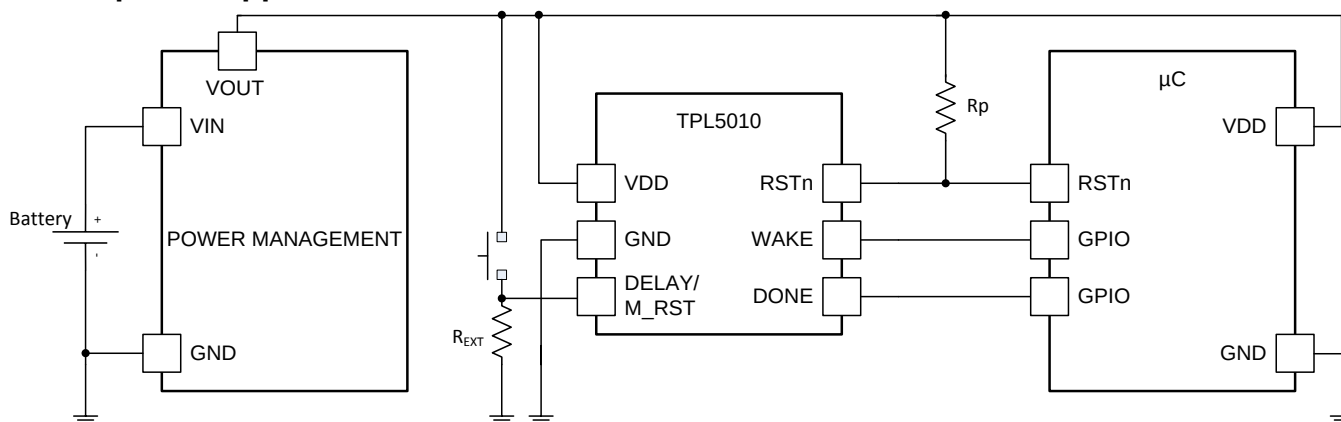


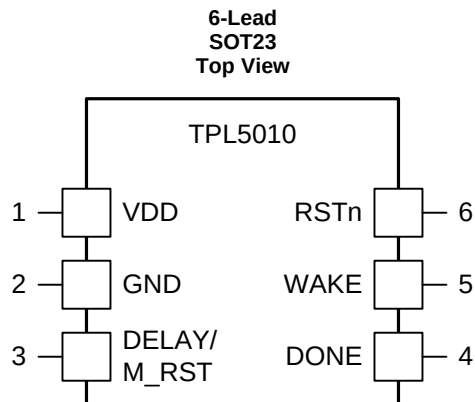
Table of Contents

1 Features	1	8.2 Functional Block Diagram	8
2 Applications	1	8.3 Feature Description	8
3 Description	1	8.4 Device Functional Modes	9
4 Simplified Application Schematic	1	8.5 Programming	9
5 Revision History	2	9 Application and Implementation	15
6 Pin Configuration and Functions	3	9.1 Application Information	15
7 Specifications	4	9.2 Typical Application	15
7.1 Absolute Maximum Ratings	4	10 Power Supply Recommendations	17
7.2 ESD Ratings	4	11 Layout	17
7.3 Recommended Operating Ratings	4	11.1 Layout Guidelines	17
7.4 Thermal Information	4	11.2 Layout Example	17
7.5 Electrical Characteristics	5	12 Device and Documentation Support	18
7.6 Timing Requirements	6	12.1 Trademarks	18
7.7 Typical Characteristics	7	12.2 Electrostatic Discharge Caution	18
8 Detailed Description	8	12.3 Glossary	18
8.1 Overview	8	13 Mechanical, Packaging, and Orderable Information	18

5 Revision History

DATE	REVISION	NOTES
January 2015	*	Initial release.

6 Pin Configuration and Functions



Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION	APPLICATION INFORMATION
NO.	NAME			
1	VDD	P	Supply voltage	
2	GND	G	Ground	
3	DELAY/ M_RST	I	Time Interval set and Manual Reset	Resistance between this pin and GND is used to select the time interval. The reset switch is also connected to this pin.
4	DONE	I	Logic Input for watchdog functionality	Digital signal driven by the μ C to indicate successful processing of the WAKE signal.
5	WAKE	O	Timer output signal generated every t_{IP} period.	Digital pulsed signal to wake up the μ C at the end of the programmed time interval.
6	RSTn	O	Reset Output (open drain output)	Digital signal to RESET the μ C, pull-up resistance is required

(1) G= Ground, P= Power, O= Output, I= Input.

7 Specifications

7.1 Absolute Maximum Ratings⁽¹⁾

	MIN	MAX	UNIT
Supply Voltage (VDD-GND)	-0.3	6.0	V
Input Voltage at any pin ⁽²⁾	-0.3	VDD + 0.3	V
Input Current on any pin	-5	+5	mA
Storage Temperature, T _{stg}	-65	150	°C
Junction Temperature, T _J ⁽³⁾		150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The voltage between any two pins should not exceed 6V.
- (3) The maximum power dissipation is a function of T_J(MAX), θ_{JA}, and the ambient temperature, T_A. The maximum allowable power dissipation at any ambient temperature is P_{DMAX} = (T_J(MAX) - T_A) / θ_{JA}. All numbers apply for packages soldered directly onto a PC board.

7.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human Body Model, per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±1000	V
		Charged-device model (CDM), per JEDEC specification JESD22-101 ⁽²⁾	±250	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Ratings

	MIN	MAX	UNIT
Supply Voltage (VDD-GND)	1.8	5.5	V
Temperature Range	-40	105	°C

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPL5010	UNIT
		SOT23	
		6 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	163	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	26	
R _{θJB}	Junction-to-board thermal resistance	57	
Ψ _{JT}	Junction-to-top characterization parameter	7.5	
Ψ _{JB}	Junction-to-board characterization parameter	57	
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

7.5 Electrical Characteristics⁽¹⁾

Specifications are for $T_A = 25^\circ\text{C}$, $V_{DD-GND} = 2.5\text{ V}$, unless otherwise stated.

	PARAMETER	TEST CONDITIONS		MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
POWER SUPPLY							
IDD	Supply current ⁽⁴⁾	Operation mode		35	50		nA
		Digital conversion of external resistance (Rext)		200	400		μA
TIMER							
t _{IP}	Time Interval Period	1650 selectable Time Intervals	Min time interval	100			ms
			Max time interval	7200			s
	Time Interval Setting Accuracy ⁽⁵⁾	Excluding the precision of Rext		±0.6%			
	Timer Interval Setting Accuracy over supply voltage	1.8V ≤ VDD ≤ 5.5V		±25			ppm/V
t _{OSC}	Oscillator Accuracy			-0.5%	0.5%		
	Oscillator Accuracy over temperature ⁽⁶⁾	-40°C ≤ T _A ≤ 105°C		±100	±400		ppm/°C
	Oscillator Accuracy over supply voltage	1.8V ≤ VDD ≤ 5.5V		±0.4			%/V
	Oscillator Accuracy over life time ⁽⁷⁾			0.24%			
t _{DONE}	DONE Pulse width ⁽⁶⁾			100			ns
t _{RSTn}	RSTn Pulse width			320			ms
t _{WAKE}	WAKE Pulse width			20			ms
t _{_Rext}	Time to convert Rext			100	120		ms
DIGITAL LOGIC LEVELS							
VIH	Logic High Threshold DONE pin			0.7xVDD			V
VIL	Logic Low Threshold DONE pin			0.3xVDD			V
VOH	Logic output High Level WAKE pin	Iout = 100 μA		VDD-0.3			V
		Iout = 1 mA		VDD-0.7			V
VOL	Logic output Low Level WAKE pin	Iout = -100 μA		0.3			V
		Iout = -1 mA		0.7			V
VOL _{RSTn}	RSTn Logic output Low Level	IOL= -1 mA		0.3			V
IOH _{RSTn}	RSTn High Level output current	VOH _{RSTn} =VDD		1			nA
VIH _{M_RST}	Logic High Threshold DELAY/M_RST pin			1.5			V

- (1) Electrical Characteristics Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that $T_J = T_A$. No specification of parametric performance is indicated in the electrical tables under conditions of internal self-heating where $T_J > T_A$. Absolute Maximum Ratings indicate junction temperature limits beyond which the device may be permanently degraded, either mechanically or electrically.
- (2) Limits are specified by testing, design, or statistical analysis at 25°C . Limits over the operating temperature range are specified through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not specified on shipped production material.
- (4) The supply current excludes load and pull-up resistor current. Input pins are at GND or VDD.
- (5) The accuracy for time interval settings below 1second is $\pm 100\text{ms}$.
- (6) This parameter is specified by design and/or characterization and is not tested in production.
- (7) Operational life time test procedure equivalent to 10 years.

7.7 Typical Characteristics

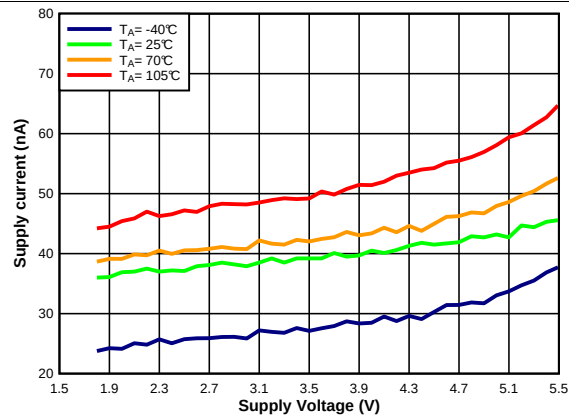


Figure 2. I_{DD} vs. V_{DD}

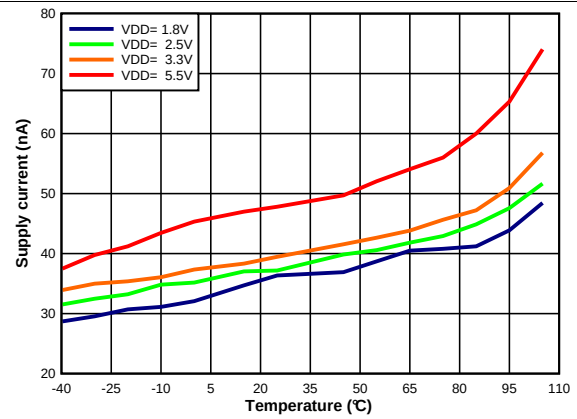


Figure 3. I_{DD} vs. Temperature

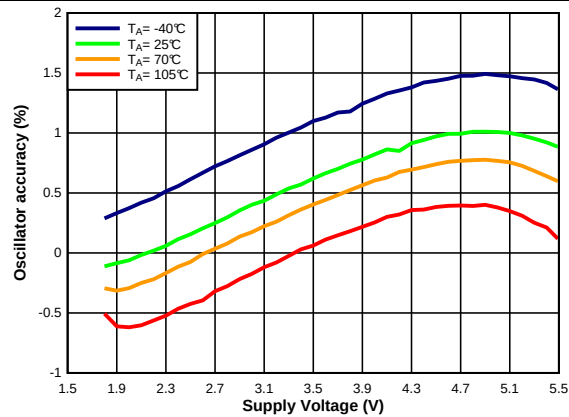


Figure 4. Oscillator Accuracy vs. V_{DD}

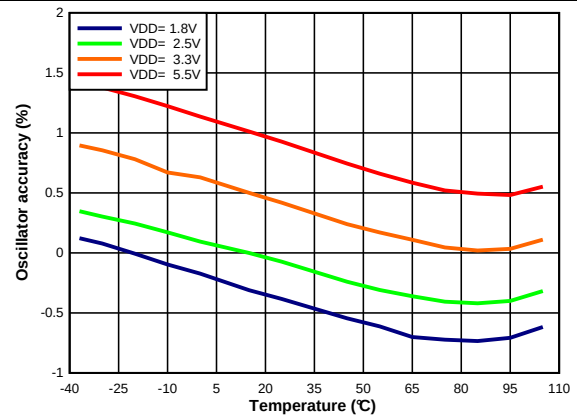


Figure 5. Oscillator Accuracy vs. Temperature

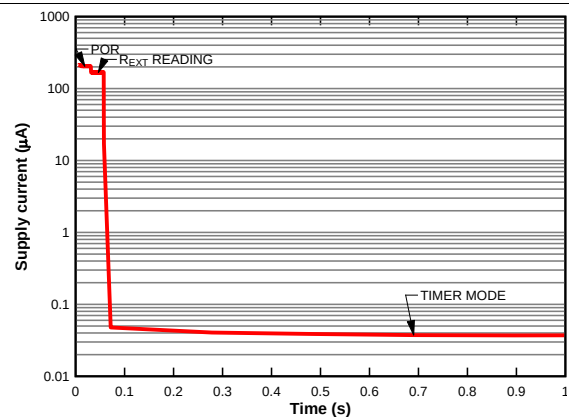


Figure 6. I_{DD} vs. Time

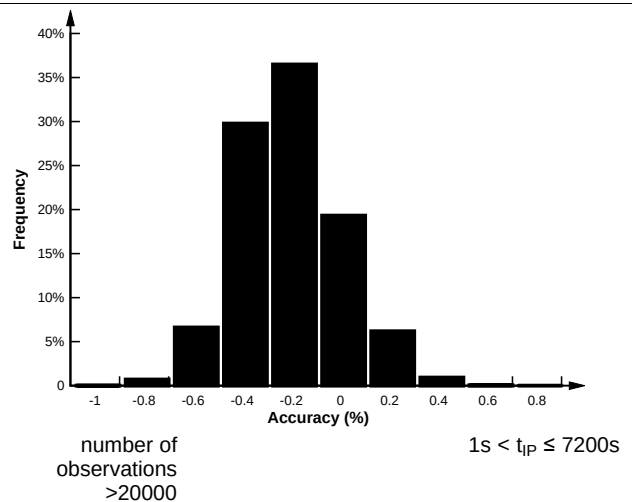


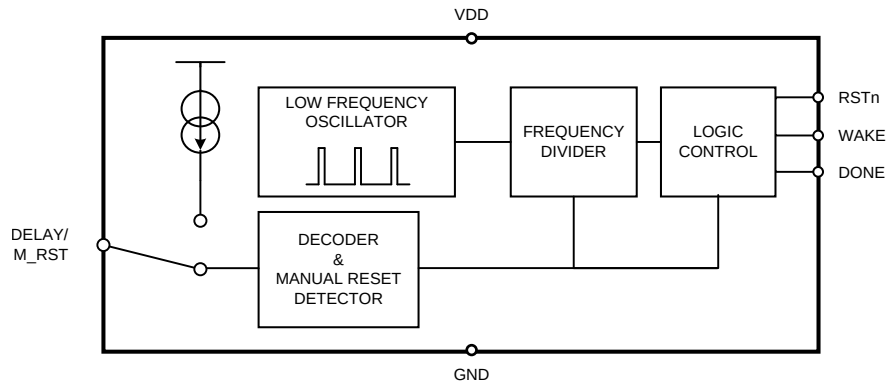
Figure 7. Time Interval Setting Accuracy

8 Detailed Description

8.1 Overview

The TPL5010 is a system wakeup timer with a watchdog feature, ideal for low power applications. TPL5010 is ideal for use in interrupt-driven applications and provides selectable timing from 100ms to 7200s.

8.2 Functional Block Diagram



8.3 Feature Description

The DONE, WAKE and RSTn signals are used to implement the watchdog function. The TPL5010 is programmed to issue a periodic WAKE pulse to a μ C which is in sleep or standby mode. After receiving the WAKE pulse, the μ C must issue a DONE signal to the TPL5010 at least 20ms before the rising edge of the next WAKE pulse. If the DONE signal is not asserted, the TPL5010 asserts the RSTn signal to reset the μ C. A manual reset function is realized by momentarily pulling the DELAY/M_RST pin to VDD.

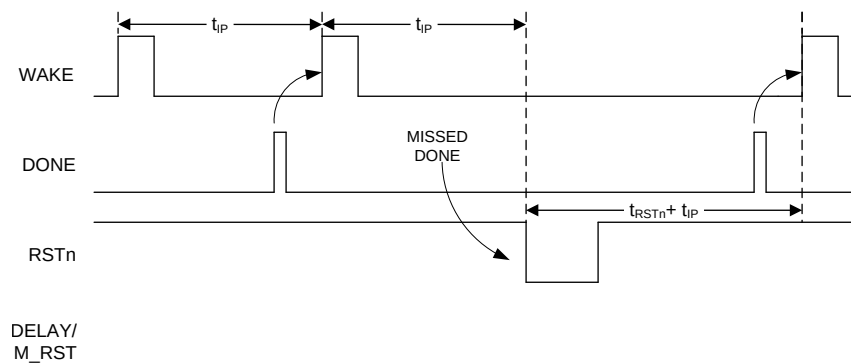


Figure 8. Watchdog

8.3.1 WAKE

The WAKE pulse is sent out from the TPL5010 when the programmed time interval starts (except at the beginning of the first cycle or if in the previous interval the DONE has not been received).

This signal is normally low.

8.3.2 DONE

The DONE pin is driven by a μ C to signal successful processing of the WAKE signal. The TPL5010 recognizes a valid DONE signal as a low to high transition; if two or more DONE signals are received within the time interval, only the first DONE signal is processed.

The DONE signal resets the counter of the watchdog only. If the DONE signal is received when the WAKE is still high, the WAKE will go low as soon as the DONE is recognized.

Feature Description (continued)

8.3.3 RSTn

To implement the reset interface between the TPL5010 and the uC a pull-up resistance is required. 100KΩ is recommended, to minimize current.

During the POR and the reading of the REXT the RSTn signal is LOW.

RSTn is asserted (LOW) for either one of the following conditions:

- 1. If the DELAY/M_RST pin is high for at least two consecutive cycles of the internal oscillator (approximately 20ms).
- 2. At the beginning of a new time interval if DONE is not received at least 20 ms before the next WAKE rising edge (see [Figure 8](#)).

8.4 Device Functional Modes

8.4.1 Startup

During startup, after POR, the TPL5010 executes a one-time measurement of the resistance attached to the DELAY/M_RST pin in order to determine the desired time interval for WAKE. This measurement interval is t_{R_EXT} . During this measurement a constant current is temporarily flowing into R_{EXT} .

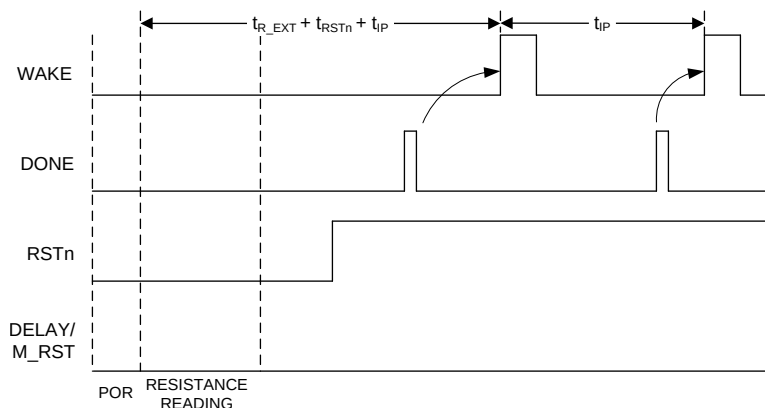


Figure 9. Startup

8.4.2 Normal Operating Mode

During normal operating mode, the TPL5010 asserts periodic WAKE pulses in response to valid DONE pulses from the uC. If either a manual reset is applied (logic HIGH on DELAY/M_RST pin) or the uC does not issue a DONE pulse within the required time, the TPL5010 asserts the RSTn signal to the uC and restarts its internal counters. See [Figure 8](#) and [Figure 10](#).

8.5 Programming

8.5.1 Configuring the WAKE Interval with the DELAY/M_RST Pin

The time interval between 2 adjacent WAKE pulses (rising edges) is selectable through an external resistance (R_{EXT}) between the DELAY/M_RST pin and ground. The value of the resistance R_{EXT} is converted one time after POR. The allowable range of R_{EXT} is 500Ω to 170kΩ. At least a 1% precision resistance is recommended. See section [Timer Interval Selection Using External Resistance](#) on how to set the WAKE pulse interval using R_{EXT} .

The time between 2 adjacent RESET signals (falling edges) or between a RESET (falling edge) and a WAKE (rising edge) is given by the sum of the programmed time interval and the t_{RSTn} (reset pulse width).

Programming (continued)

8.5.2 Manual Reset

If VDD is connected to the DELAY/M_RST pin, the TPL5010 recognizes this as a manual reset condition. In this case the time interval is not set. If the manual reset is asserted during the POR or during the reading procedure, the reading procedure is aborted and is re-started as soon as the manual reset switch is released. A pulse on the DELAY/M_RST pin is recognized as a valid manual reset only if it lasts at least 20ms (observation time is 30ms).

A valid manual reset resets all the counters inside the TPL5010. The counters restart only when the high digital voltage at DELAY/M_RST is removed and the next t_{RSTn} is elapsed.

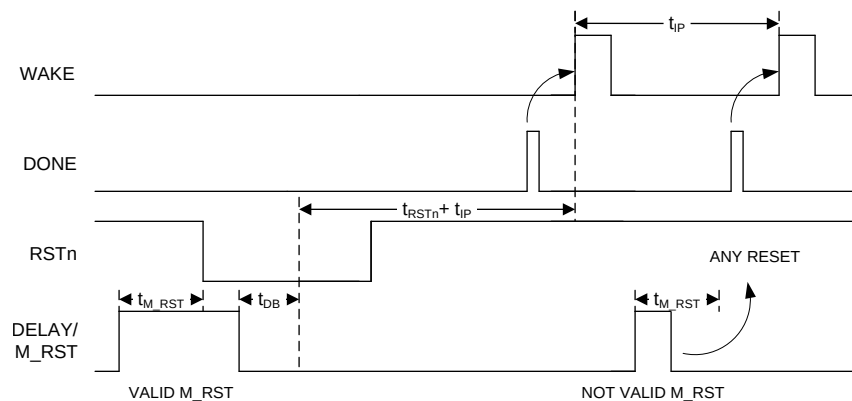


Figure 10. Manual Reset

8.5.2.1 DELAY/M_RST

A resistance in the range between 500Ω and 170kΩ needs to be connected in order to select a valid time interval. At the POR and during the reading of the resistance the DELAY/M_RST is connected to an analog signal chain through a mux. After the reading of the resistance the analog circuit is switched off and the DELAY/RST is connected to a digital circuit.

The manual reset detection is supported with a de-bounce feature which makes the TPL5010 insensitive to the glitches on the DELAY/M_RST pin. When a valid manual reset signal is asserted on the DELAY/M_RST pin, the RSTn signal is asserted LOW after a delay of t_{M_RST} . It remains LOW after a valid manual reset is asserted + t_{DB} + t_{RSTn} . Due to the asynchronous nature of the manual reset signal and its arbitrary duration, the LOW status of the RSTn signal maybe affected by an uncertainty of about ±5ms.

A valid manual reset puts all the digital output signals at their default values:

- WAKE = LOW
- RSTn = asserted LOW

8.5.2.2 Circuitry

The manual reset may be implemented using a switch (momentary mechanical action). The TPL5010 offers 2 possible approaches according to the power consumption constraints of the application.

Programming (continued)

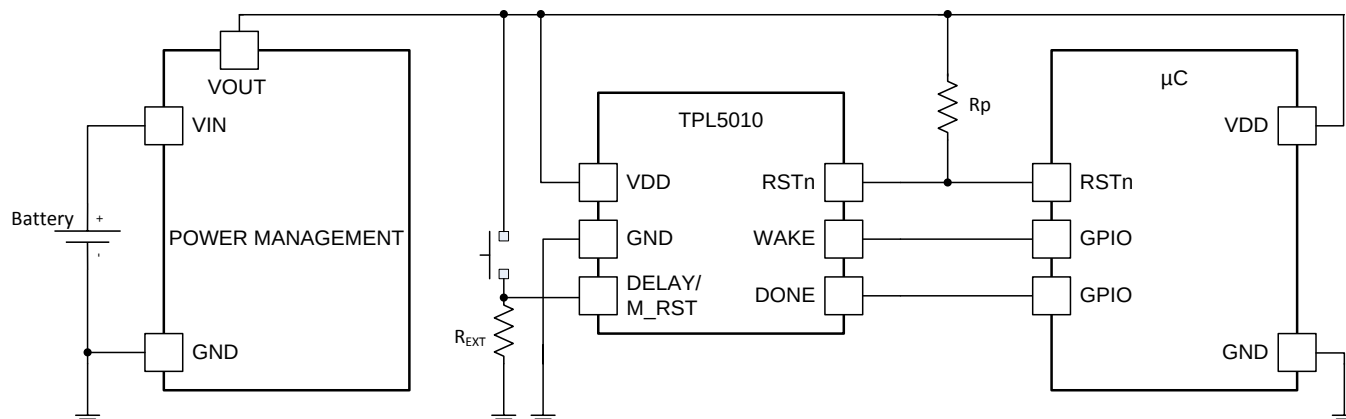


Figure 11. Manual Reset with SPST Switch

For use cases that do not require the lowest power consumption, using a single pole single throw switch may offer a lower cost solution. The DELAY/M_RST pin may be directly connected to VDD with R_{EXT} in the circuit. The current drawn from the supply voltage during the reset is given by VDD/R_{EXT} .

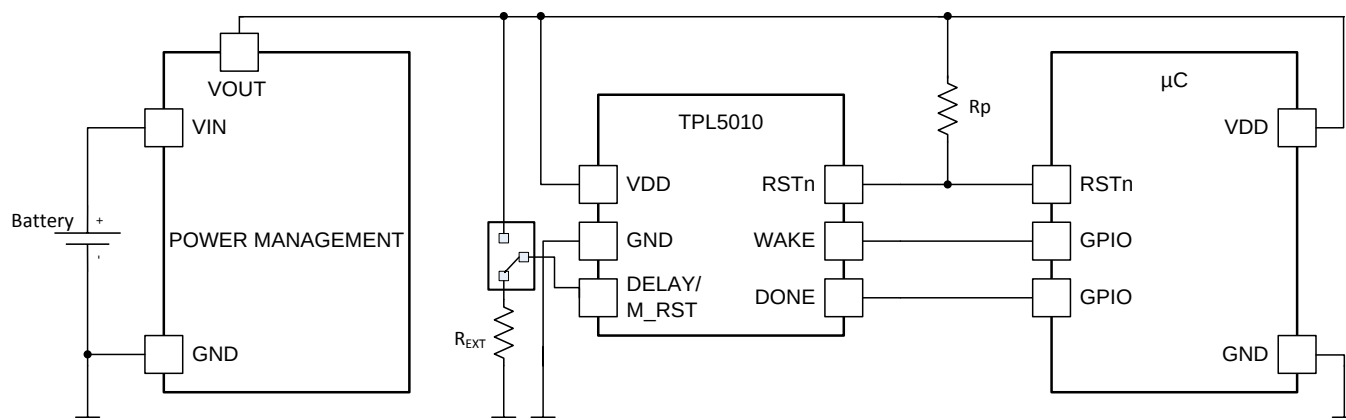


Figure 12. Manual Reset with SPDT Switch

The reset function may also be asserted by switching DELAY/M_RST from R_{EXT} to VDD using a single pole double throw switch, which will provide a lower power solution for the manual reset, because no current flows.

8.5.3 Timer Interval Selection Using External Resistance

In order to set the time interval, the external resistance R_{EXT} is selected according the following formula:

$$R_{EXT} = 100 \left(\frac{-b + \sqrt{b^2 - 4a(c - 100T)}}{2a} \right) \quad (1)$$

Where:

- **T** is the desired time interval in seconds.
- **R_{EXT}** is the resistance value to use in Ω .
- **a,b,c** are coefficients depending on the range of the time interval.

Programming (continued)

Table 1. Coefficients for Equation 1

SET	Time interval Range (s)	a	b	c
1	1 < T ≤ 5	0.2253	-20.7654	570.5679
2	5 < T ≤ 10	-0.1284	46.9861	-2651.8889
3	10 < T ≤ 100	0.1972	-19.3450	692.1201
4	100 < T ≤ 1000	0.2617	-56.2407	5957.7934
5	T > 1000	0.3177	-136.2571	34522.4680

EXAMPLE

Required time interval: 8s

The coefficient set to be selected is the number 2. The formula becomes

$$R_{EXT} = 100 \left(\frac{46.9861 - \sqrt{46.9861^2 + 4 * 0.1284 (-2651.8889 - 100 * 8)}}{2 * 0.1284} \right) \quad (2)$$

The resistance value is 10.18 kΩ.

The following Look-Up-Tables contain example values of t_{IP} and their corresponding value of R_{EXT}.

Table 2. First 9 Time Intervals

t _{IP} (ms)	Resistance (Ω)	Closest Real Value (Ω)	Parallel of Two 1% Tolerance Resistors, (kΩ)
100	500	500	1.0 // 1.0
200	1000	1000	-
300	1500	1500	2.43 // 3.92
400	2000	2000	-
500	2500	2500	4.42 // 5.76
600	3000	3000	5.36 // 6.81
700	3500	3500	4.75 // 13.5
800	4000	4000	6.19 // 11.3
900	4500	4501	6.19 // 16.5

Table 3. Most Common Time Intervals Between 1s to 2h

t _{IP}	Calculated Resistance (kΩ)	Closest Real Value (kΩ)	Parallel of Two 1% Tolerance Resistors, (kΩ)
1s	5.20	5.202	7.15 // 19.1
2s	6.79	6.788	12.4 // 15.0
3s	7.64	7.628	12.7 // 19.1
4s	8.30	8.306	14.7 // 19.1
5s	8.85	8.852	16.5 // 19.1
6s	9.27	9.223	18.2 // 18.7
7s	9.71	9.673	19.1 // 19.6
8s	10.18	10.180	11.5 // 8.87
9s	10.68	10.68	17.8 // 26.7
10s	11.20	11.199	15.0 // 44.2
20s	14.41	14.405	16.9 // 97.6
30s	16.78	16.778	32.4 // 34.8
40s	18.75	18.748	22.6 // 110.0
50s	20.047	20.047	28.7 // 66.5

Table 3. Most Common Time Intervals Between 1s to 2h (continued)

t_P	Calculated Resistance (k Ω)	Closest Real Value (k Ω)	Parallel of Two 1% Tolerance Resistors, (k Ω)
1min	22.02	22.021	40.2 // 48.7
2min	29.35	29.349	35.7 // 165.0
3min	34.73	34.729	63.4 // 76.8
4min	39.11	39.097	63.4 // 102.0
5min	42.90	42.887	54.9 // 196.0
6min	46.29	46.301	75.0 // 121.0
7min	49.38	49.392	97.6 // 100.0
8min	52.24	52.224	88.7 // 127.0
9min	54.92	54.902	86.6 // 150.0
10min	57.44	57.437	107.0 // 124.0
20min	77.57	77.579	140.0 // 174.0
30min	92.43	92.233	182.0 // 187.0
40min	104.67	104.625	130.0 // 536.00
50min	115.33	115.331	150.0 // 499.00
1h	124.91	124.856	221.0 // 287.00
1h30min	149.39	149.398	165.0 // 1580.0
2h	170.00	170.00	340.0 // 340.0

8.5.4 Quantization Error

The TPL5010 can generate 1650 discrete timer intervals in the range of 100ms to 7200s. The first 9 intervals are multiples of 100ms. The remaining 1641 intervals cover the range between 1s to 7200s. Because they are discrete intervals, there is a quantization error associated with each value.

The quantization error can be evaluated according to the following formula:

$$Err = 100 \frac{(T_{DESIRED} - T_{ADC})}{T_{DESIRED}} \quad (3)$$

Where:

$$T_{ADC} = INT \left[\frac{1}{100} \left(a \frac{R_D^2}{100^2} + b \frac{R_D}{100} + c \right) \right] \quad (4)$$

$$R_D = INT \left[\frac{R_{EXT}}{100} \right] \quad (5)$$

R_{EXT} is the resistance calculated with Equation 1 and a,b,c are the coefficients of the equation listed in Table 1.

8.5.5 Error Due to Real External Resistance

R_{EXT} is a theoretical value and may not be available in standard commercial resistor values. It is possible to closely approach the theoretical R_{EXT} using two or more standard values in parallel. However, standard values are characterized by a certain tolerance. This tolerance will affect the accuracy of the time interval.

The accuracy can be evaluated using the following procedure:

1. Evaluate the min and max values of R_{EXT} (R_{EXT_MIN} , R_{EXT_MAX} with Equation 1 using the selected commercial resistance values and their tolerances.
2. Evaluate the time intervals ($T_{ADC_MIN}[R_{EXT_MIN}]$, $T_{ADC_MAX}[R_{EXT_MAX}]$) with Equation 4.
3. Find the errors using Equation 3 with T_{ADC_MIN} , T_{ADC_MAX} .

The results of the formula indicate the accuracy of the time interval.

The example below illustrates the procedure.

- Desired time interval , $T_{desired} = 600s$,

- Required R_{EXT} , from [Equation 1](#), $R_{EXT} = 57.44\text{k}\Omega$.

From [Table 3](#) R_{EXT} can be built with a parallel combination of two commercial values with 1% tolerance: $R1 = 107\text{k}\Omega$, $R2 = 124\text{k}\Omega$. The uncertainty of the equivalent parallel resistance can be found using:

$$uR_{//} = R_{//} \sqrt{\left(\frac{u_{R1}}{R1}\right)^2 + \left(\frac{u_{R2}}{R2}\right)^2} \quad (6)$$

Where uR_n ($n=1,2$) represent the uncertainty of a resistance,

$$u_{R_n} = R_n \frac{\text{Tolerance}}{\sqrt{3}} \quad (7)$$

The uncertainty of the parallel resistance is 0.82%, meaning the value of R_{EXT} may range between $R_{EXT_MIN} = 56.96\text{ k}\Omega$ and $R_{EXT_MAX} = 57.90\text{ k}\Omega$.

Using these value of R_{EXT} , the digitized timer intervals calculated with [Equation 4](#) are respectively $T_{ADC_MIN} = 586.85\text{s}$ and $T_{ADC_MAX} = 611.3\text{s}$, giving an error range of -1.88% / +2.19%. The asymmetry of the error range is due to the quadratic transfer function of the resistance digitizer.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

In battery powered applications one design constraint is the need for low current consumption. The TPL5010 is ideal for applications where there is a need to monitor environmental conditions at a fixed time interval. Often in these applications a watchdog or other internal timer in a μC is used to implement a wakeup function. Using the TPL5010 to implement the watchdog function will consume only tens of nA, significantly improving the power consumption of the system.

9.2 Typical Application

The TPL5010 can be used in conjunction with environment sensors to build a low power environment data-logger, such as an air quality data-logger. In this application, due to the monitored phenomena, the μC and the front end of the sensor spend most of the time in the idle state, waiting for the next logging interval, usually a few hundred of milliseconds. Figure 13 illustrates a data logging application based on a μC , and a front end for a gas sensor based on the LMP91000.

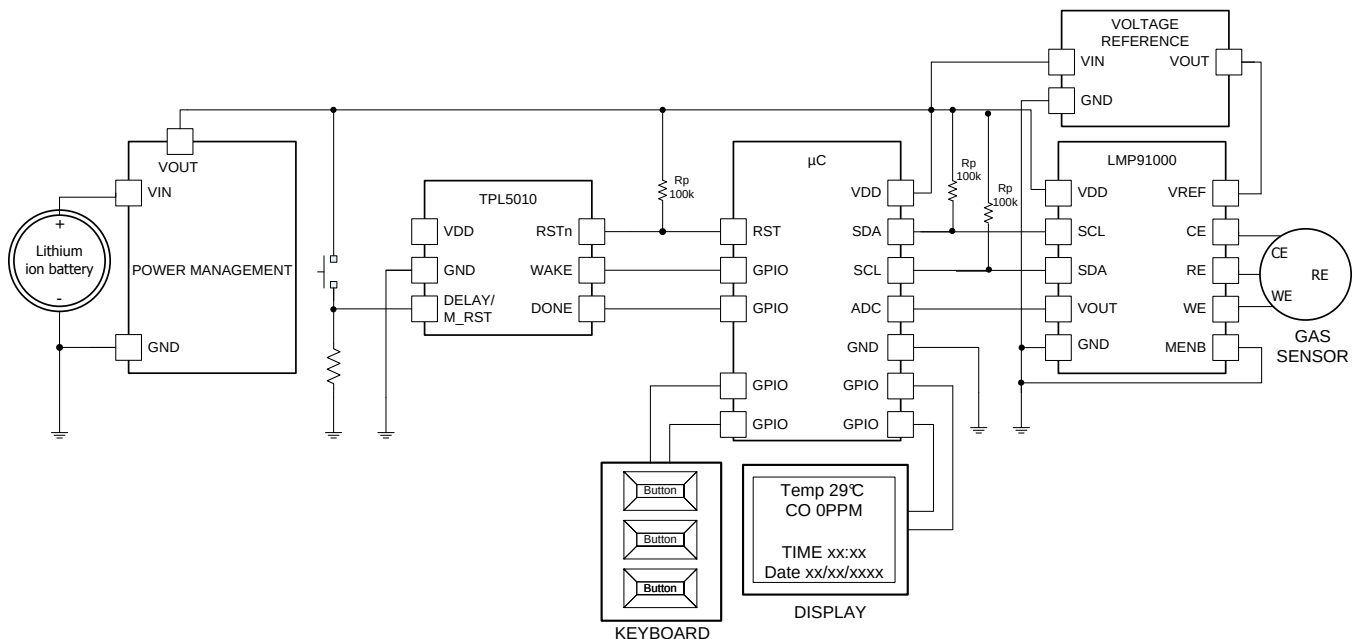


Figure 13. Data-logger

9.2.1 Design Requirements

The Design is driven by the low current consumption constraint. The data are usually acquired on a rate that ranges between 1s and 10s. The highest necessity is the maximization of the battery life. The TPL5010 helps achieve that goal because it allows putting the μC in its lowest power mode. The TPL5010 will take care of the watchdog and the timing.

Typical Application (continued)

9.2.2 Detailed Design Procedure

When the main constraint is the battery life, the selection of a low power voltage reference, μC and display is mandatory. The first step in the design is the calculation of the power consumption of the devices in their different mode of operations. For instance the LMP91000 burns most of the power when in gas measurement mode, then according to the connected gas sensor it has 2 idle states (stand-by and deep sleep). The same is true for the μC , such as one of the MSP430 family, which can be placed in one of its lower power modes, such as LMP3.5 or LMP4.5. In this case, the TPL5010 can be used to implement the watchdog and wakeup timing functions.

After the power budget calculation it is possible to select the appropriate time interval which satisfies the application constraints and maximize the life of the battery.

9.2.3 Application Curves

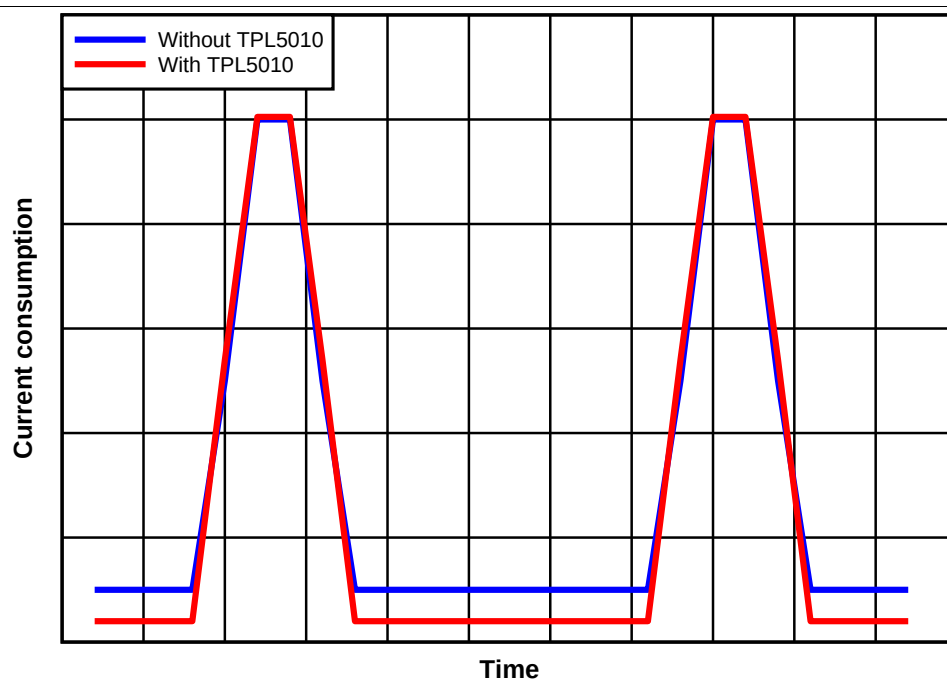


Figure 14. Effect of TPL5010 on Current Consumption

10 Power Supply Recommendations

The TPL5010 requires a voltage supply within 1.8V and 5.5V. A multilayer ceramic bypass X7R capacitor of 0.1μF between VDD and GND pin is recommended.

11 Layout

11.1 Layout Guidelines

The DELAY/M_RST pin is sensitive to parasitic capacitance. It is suggested that the traces connecting the resistance on this pin to GROUND be kept as short as possible to minimize parasitic capacitance. This capacitance can affect the initial set up of the time interval. Signal integrity on the WAKE and RSTn pins is also improved by keeping the trace length between the TPL5010 and the μC short to reduce the parasitic capacitance.

11.2 Layout Example

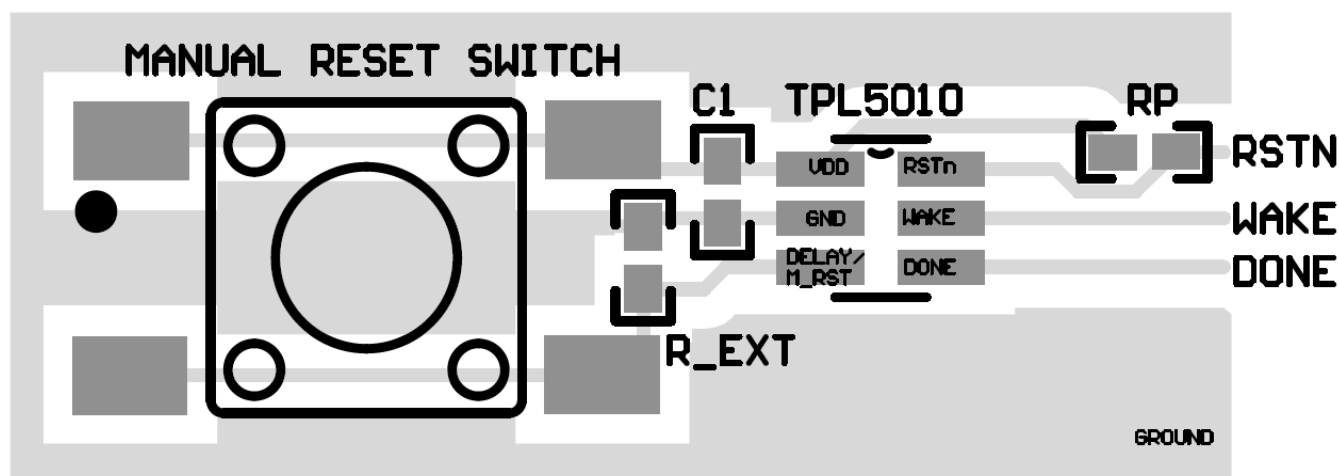


Figure 15. Layout

12 Device and Documentation Support

12.1 Trademarks

All trademarks are the property of their respective owners.

12.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPL5010DDCR	ACTIVE	SOT	DDC	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	ZAKX	Samples
TPL5010DDCT	ACTIVE	SOT	DDC	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	ZAKX	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

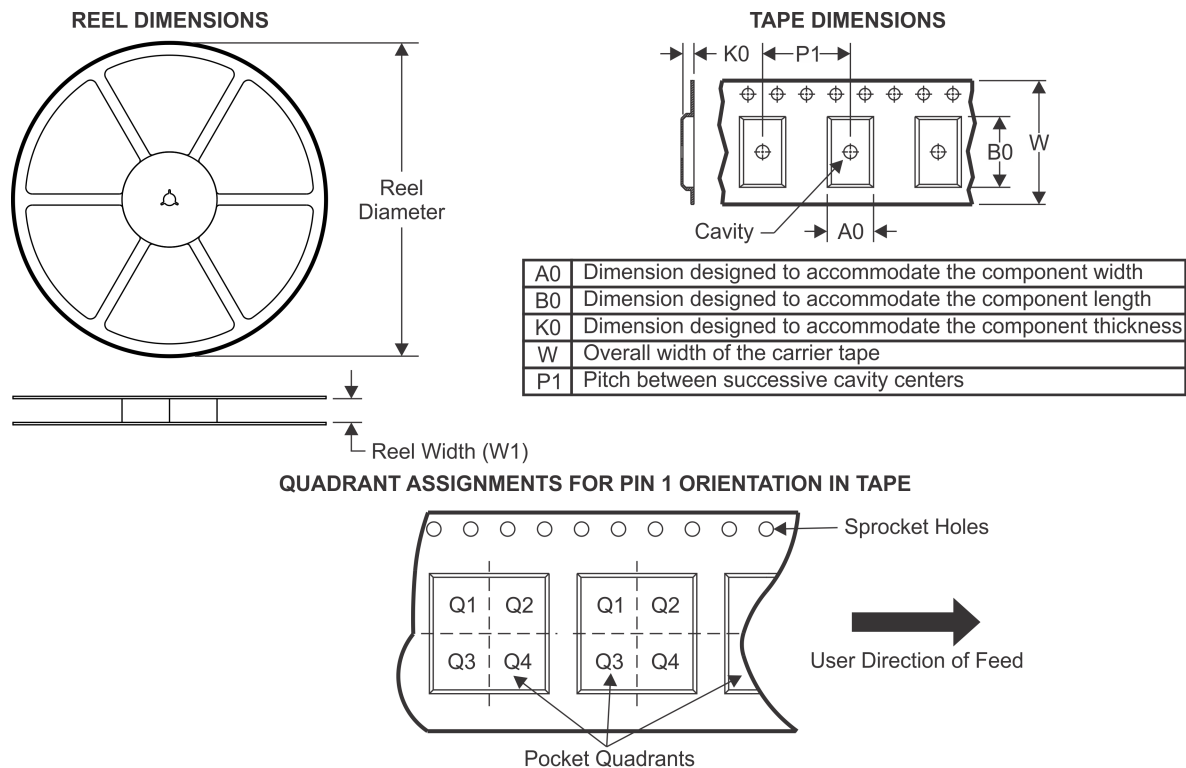
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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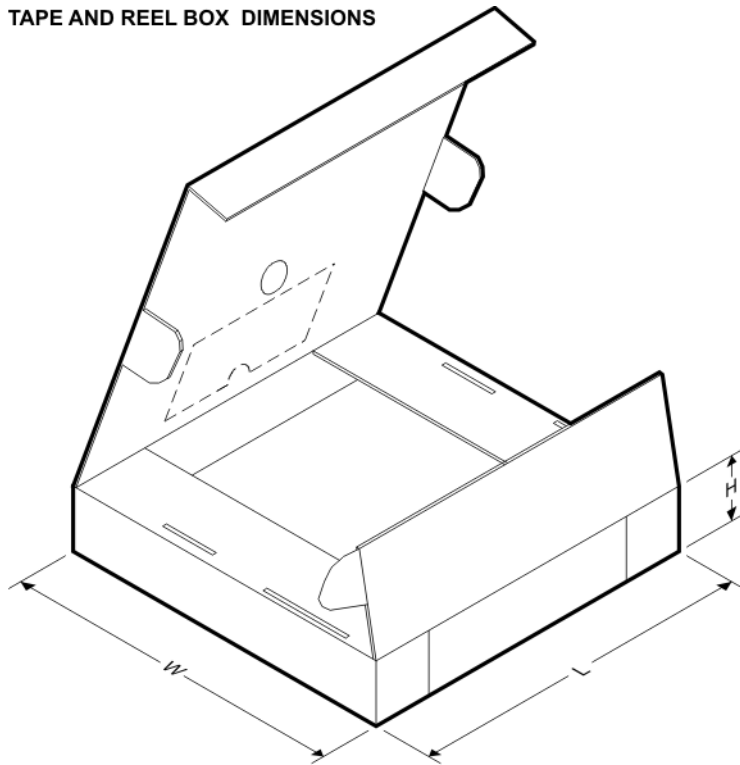
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPL5010DDCR	SOT	DDC	6	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPL5010DDCT	SOT	DDC	6	250	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

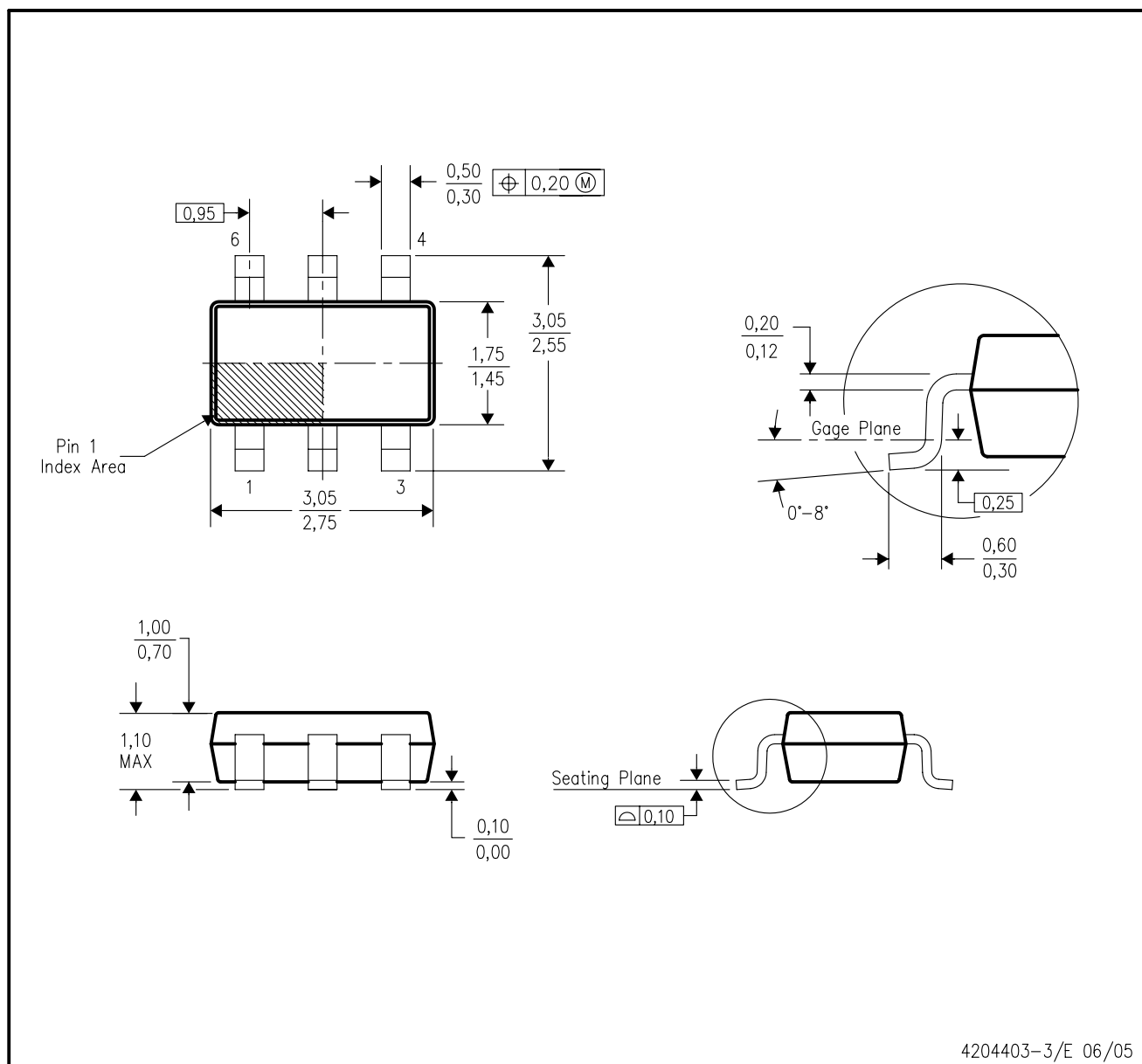


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPL5010DDCR	SOT	DDC	6	3000	210.0	185.0	35.0
TPL5010DDCT	SOT	DDC	6	250	210.0	185.0	35.0

DDC (R-PDSO-G6)

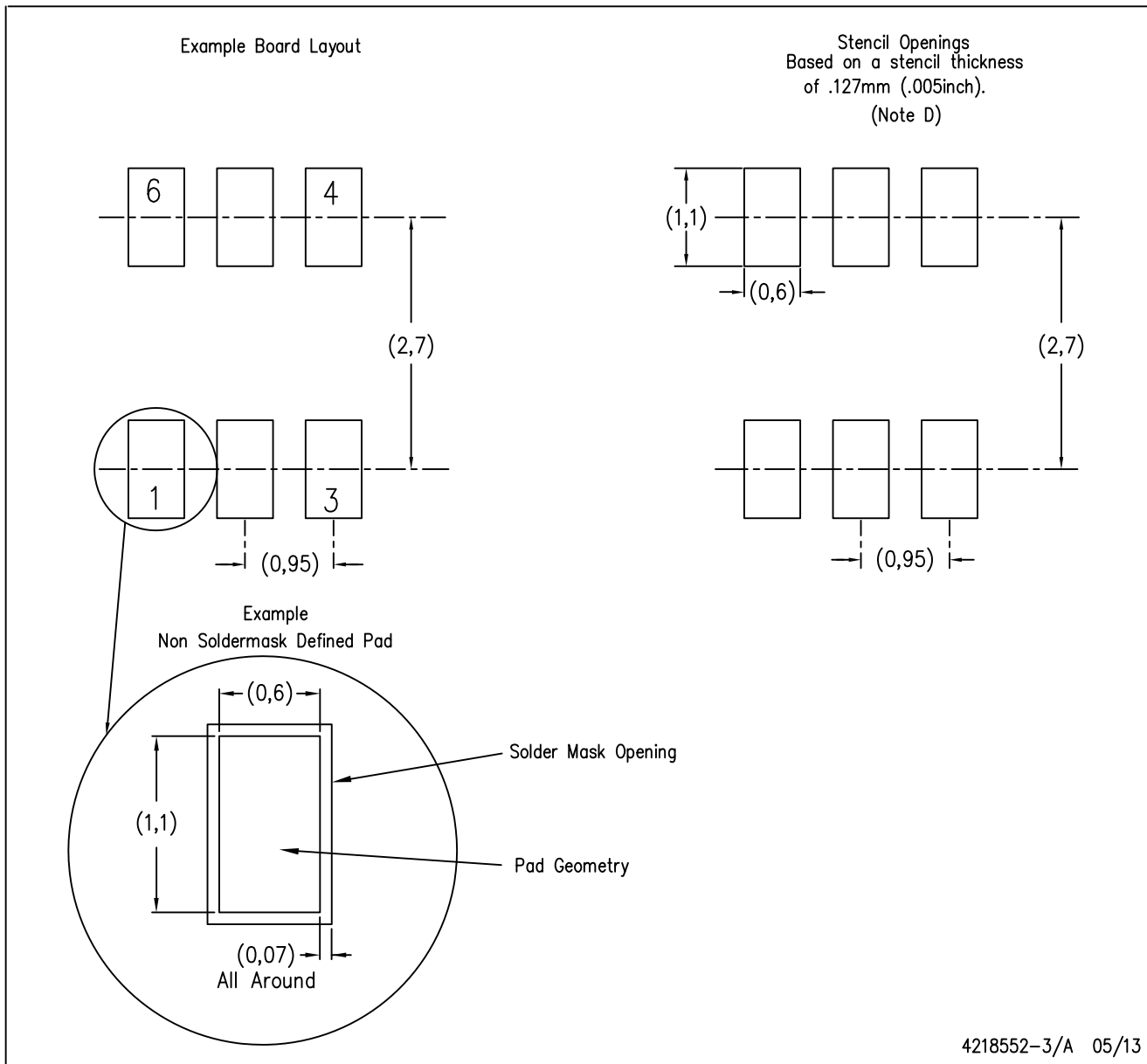
PLASTIC SMALL-OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - Falls within JEDEC MO-193 variation AA (6 pin).

DDC (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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